

DO NOT SCALE FROM THIS PRINT

HDAM-XX-XX.X-X-13-X-X

No OF POSITIONS

- (13 ROW PER POSITION)
- 11
- 15
- 23

LEAD STYLE

- 12.0: 12MM
- 17.0: 17MM

PLATING SPECIFICATION

- S: SELECTIVE, .000030 INCHES GOLD IN MATING AREA, MATTE TIN ON TAIL AND GUIDE PINS

OPTION

- P: PICK & PLACE PAD (USE MPP-26-01-N)
- SOLDER CHARGE MATERIAL**
- 1: 63%TIN / 37% LEAD
- 2: 95.5% TIN / 3.8% SILVER 0.7% COPPER (LEAD FREE)

No OF ROWS

- 13

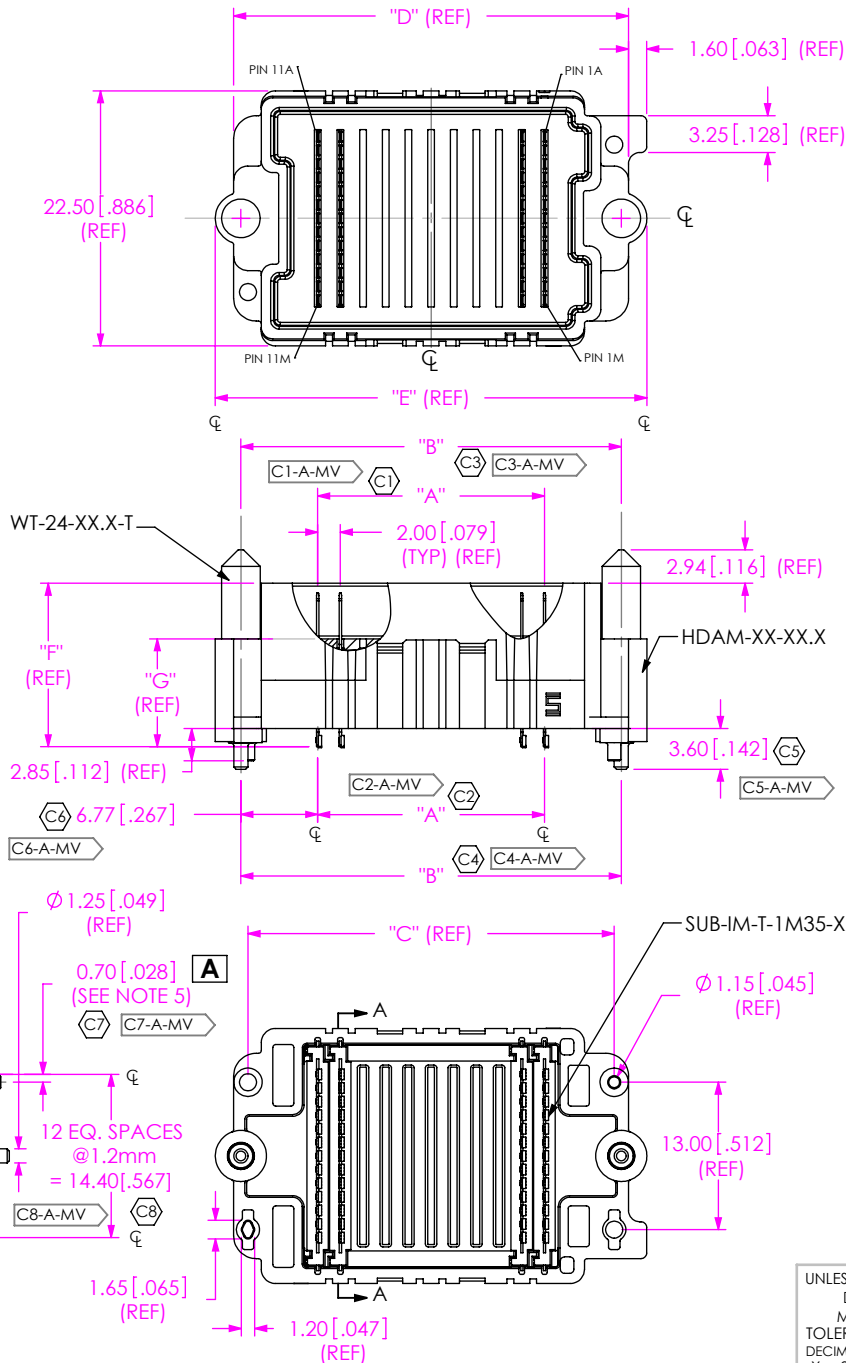


TABLE 1

STYLE	"BODY CALLOUT"	"TERMINAL WAFER"	"GUIDE PIN"
-12.0	HDAM-XX-12.0	SUB-IM-T-1M35-12.0-S-X	WT-24-12.0-T
-17.0	HDAM-XX-17.0	SUB-IM-T-1M35-17.0-S-X	WT-24-17.0-T

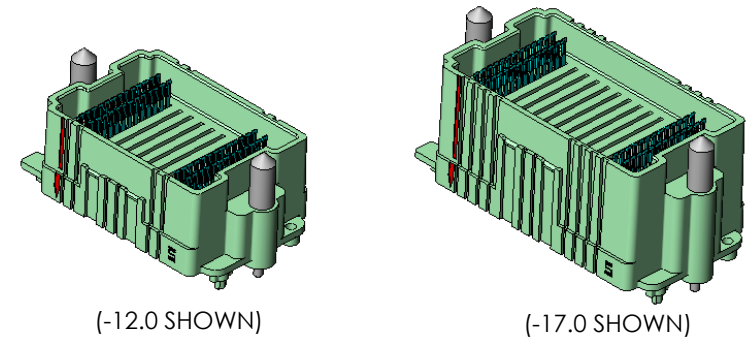
TABLE 2

STACK HEIGHT

HDAM LEAD STYLE	HDAF LEAD STYLE	
	-08.0	-18.0
-12.0	20.0MM	30.0MM
-17.0	25.0MM	35.0MM

TABLE 3

No. OF POS.	LEAD STYLE	"A"	"B"	"C"	"D"	"E"	"F"	"G"
11	12.0	20.0 [1.787]	33.55 [1.321]	32.30 [1.272]	34.82 [1.371]	38.06 [1.498]	14.41 [1.567]	9.51 [1.374]
15	12.0	28.0 [1.102]	41.55 [1.636]	40.30 [1.587]	42.82 [1.686]	46.06 [1.813]	14.41 [1.567]	9.51 [1.374]
23	12.0	44.0 [1.732]	57.55 [2.266]	56.30 [2.217]	58.82 [2.316]	62.06 [2.493]	14.41 [1.567]	9.51 [1.374]
11	17.0	20.0 [1.787]	33.55 [1.321]	32.30 [1.272]	34.82 [1.371]	38.06 [1.498]	19.41 [1.764]	14.51 [1.571]
15	17.0	28.0 [1.102]	41.55 [1.636]	40.30 [1.587]	42.82 [1.686]	46.06 [1.813]	19.41 [1.764]	14.51 [1.571]
23	17.0	44.0 [1.732]	57.55 [2.266]	56.30 [2.217]	58.82 [2.316]	62.06 [2.493]	19.41 [1.764]	14.51 [1.571]



UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN MILLIMETERS [INCHES]. TOLERANCES ARE:

DECIMALS	ANGLES
.X: ±0.3 [0.1]	2°
.XX: ±0.13 [0.05]	
.XXX: ±0.051 [0.020]	

PROPRIETARY NOTE

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SAMTEC

520 PARK EAST BLVD, NEW ALBANY, IN 47150
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MATERIAL: DO NOT SCALE DRAWING

SHEET SCALE: 1.5:1

INSULATOR: LCP, COLOR: BLACK
 CONTACT: COPPER ALLOY
 WAFER MATERIAL: LCP, COLOR: BLACK
 GUIDE PIN MATERIAL: BRASS
 PICK AND PLACE PAD: COPPER ALLOY



DESCRIPTION:
 2.0MM PITCH HD ARRAY TERMINAL ASSEMBLY

DWG. NO.
HDAM-XX-XX.X-X-13-X-X

BY: D KNOWLDEN 7/15/2005 SHEET 1 OF 2

NOTES:

1. Ⓢ REPRESENTS A CRITICAL DIMENSION.
2. MINIMUM PUSHOUT FORCE: 2.22N[.5 LB]. FOR WAFERS
3. CONNECTORS TO BE PACKAGED IN TRAYS.
4. USE THESE SURFACES TO MEASURE "G" DIMENSION.
5. DIMENSION FROM Ⓢ OF END TAIL TO Ⓢ OF -A PIN.

FIG. 1
 -11: IT POSITION
 (HDAM-11-12.0-X-13-X-X SHOWN)
 (SOME WAFERS NOT SHOWN FOR CLARITY)

**DESIGNED & DIMENSIONED IN MILLIMETERS
 (INCHES FOR REFERENCE ONLY)**

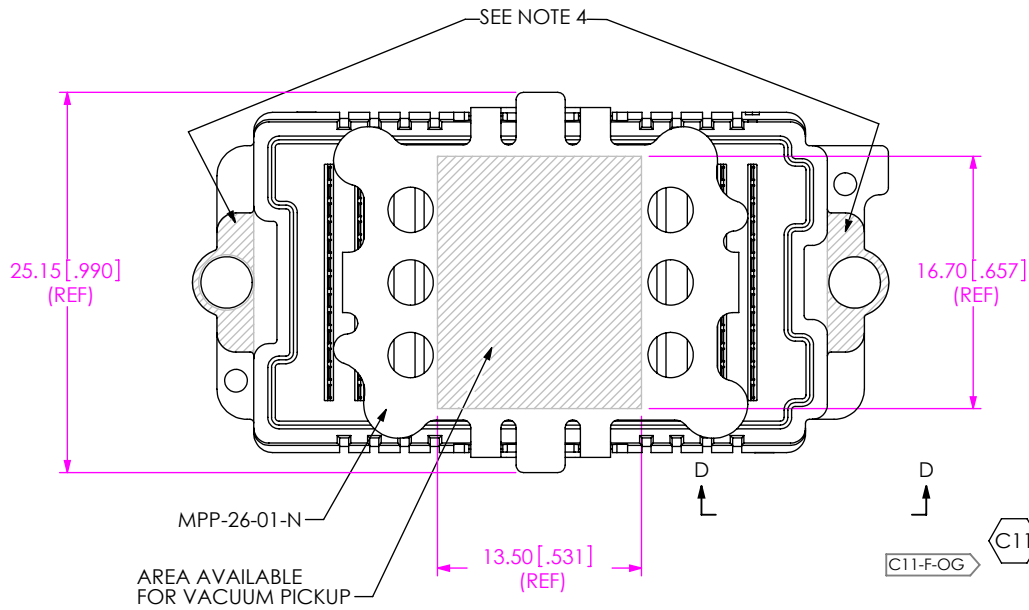
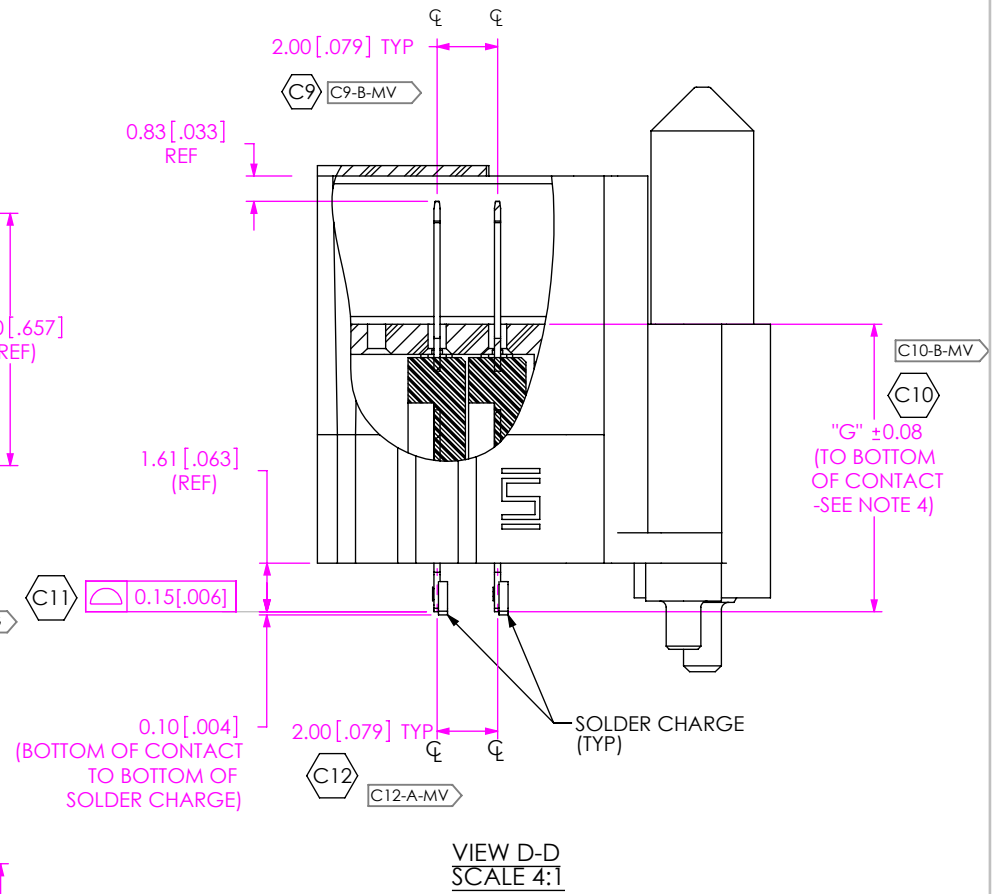
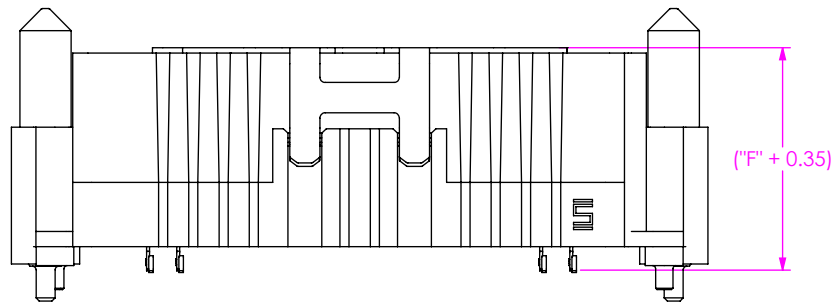


FIG. 2
-15: T5 POSITION
(HDAM-15-12.0-X-13-X-P SHOWN)
(SOME WAFERS NOT SHOWN FOR CLARITY)



VIEW D-D
SCALE 4:1

CRITICAL DIMENSION INSPECTION INSTRUCTION TABLE		
ASSEMBLY OPERATION	START-UP INSPECTION INSPECT CODE A	IN-PROCESS INSPECTION INSPECT CODE B
FILL WAFERS	C1, C2, C7, C8, C12	C9, C10
FILL WELD TABS	C2, C3, C4, C5, C6, C12	C10
INSTALL PAD	C2, C6, C12	N/A

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SHEET SCALE: 2:1

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DWG. NO.
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